



250V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| V _{(BR)DSS} | Max R _{DS(on)} | Max I _D T _A = +25°C | |
|----------------------|------------------------------|--|--|
| 250V | 8.5Ω @ V _{GS} = 10V | 230mA | |

Description and Applications

This 250V enhancement mode N-channel MOSFET provides users with a competitive specification. It offers efficient power handling capability, high impedance and is free from thermal runaway and thermally induced secondary breakdowns. Applications benefiting from this device include a variety of Telecom and general highvoltage circuits.

SOT89 and SOT223 versions are also available.

- Earth Recall and Dialing Switches
- Electronic Hook Switches
- High Voltage Power MOSFET Drivers
- Telecom Call Routers
- Solid State Relays

Features and Benefits

- High voltage
- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Complementary P-channel Type ZVP4525E6
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

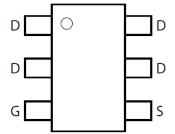
Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.015 grams (Approximate)

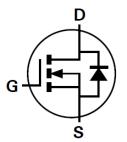








Pinout Top-view



Device symbol

Ordering Information (Note 4)

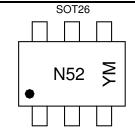
| Part Number | Reel Size (inch) | Tape Width (mm) | Quantity Per Reel |
|-------------|------------------|-----------------|-------------------|
| ZVN4525E6TA | 7 | 8 | 3,000 |
| ZVN4525E6TC | 13 | 8 | 10,000 |

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



N52 = Product Type Marking Code YM = Date Code Marking

Y or \overline{Y} = Year (ex: C = 2015)

M or \overline{M} = Month (ex: 9 = September)

Date Code Key

| Year | 2015 | 2 | 016 | 2017 | 2018 | 2019 | 2020 | 202 | 1 20 | 22 2 | 2023 | 2024 | 2025 |
|-------|------|-----|-----|------|------|------|------|-----|------|------|------|------|------|
| Code | С | | D | Е | F | G | Н | | , | J | K | L | М |
| Month | 1 | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

| | Characteristic | | Symbol | Value | Unit | |
|------------------------------|----------------|---------------------------------|-----------------|-------|------|--|
| Drain-Source Voltage | | | V_{DSS} | 250 | V | |
| Gate-Source Voltage | | | V _{GS} | ±40 | V | |
| Continuous Drain Current | 101/ | T _A =+25 °C (Note 4) | I _D | 230 | m Λ | |
| | $V_{GS} = 10V$ | T _A =+70 °C (Note 4) | | 183 | mA | |
| Pulsed Drain Current (Note 6 | 6) | | I _{DM} | 1.44 | Α | |
| Continuous Source Current (| (Body Diode) | | I _S | 1.1 | Α | |
| Pulsed Source Current (Bod | y Diode) | | I _{SM} | 1.44 | Α | |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

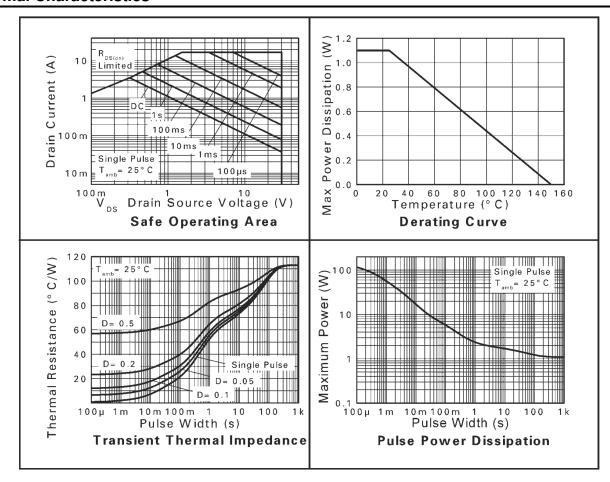
| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation at T _A =+25 °C (Note 4) | P _D | 1.1 | W |
| Linear Derating Factor | | 8.8 | mW/℃ |
| Junction to Ambient (Note 4) | $R_{	heta JA}$ | 113 | °C/W |
| Junction to Ambient (Note 5) | $R_{	heta JA}$ | 65 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | ℃ |

 For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 For a device surface mounted on FR4 PCB measured at t ≤ 5 secs. Notes:

NB High Voltage Applications

For high voltage applications, the appropriate industry sector guidelines should be considered with regards to voltage spacing between conductors.

Thermal Characteristics



^{6.} Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal.



Electrical Characteristics (@ T_A = +25 °C, unless otherwise specified.)

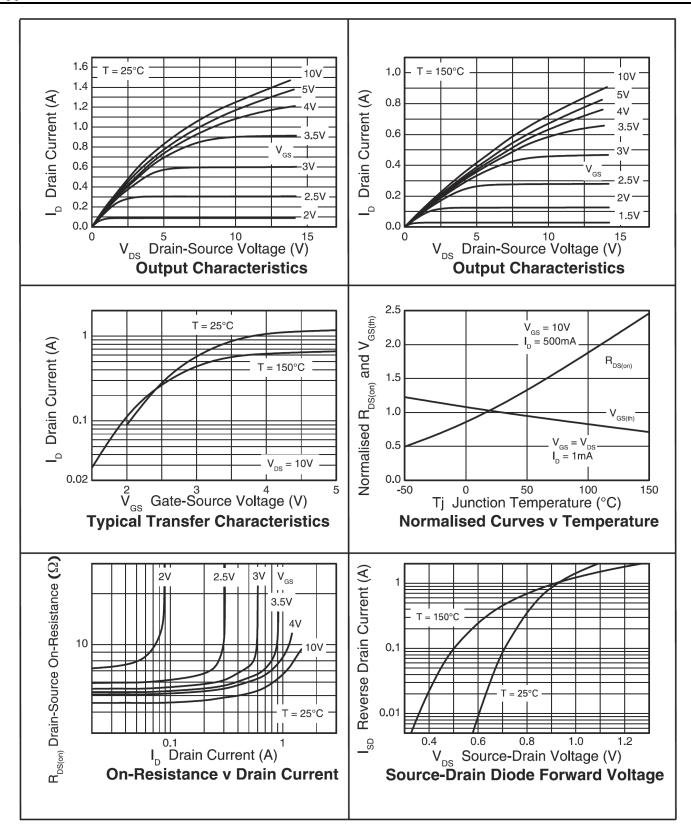
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--|----------------------|-----|-------|------|------|---|
| OFF CHARACTERISTICS | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | 250 | 285 | - | V | $I_D = 1mA$, $V_{GS} = 0V$ |
| Zero Gate Voltage Drain Current | I _{DSS} | - | 35 | 500 | νΑ | $V_{DS} = 250V, V_{GS} = 0V$ |
| Gate-Body Leakage | IGSS | | ±1 | 100 | nA | $V_{GS} = \pm 40V, V_{DS} = 0V$ |
| ON CHARACTERISTICS | | | | | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | 8.0 | 1.4 | 1.8 | V | $I_D = 1 \text{mA}, V_{DS} = V_{GS}$ |
| | | | 5.6 | 8.5 | Ω | $V_{GS} = 10V, I_D = 500mA$ |
| Static Drain-Source On-State Resistance (Note 7) | R _{DS} (ON) | - | 5.9 | 9.0 | Ω | $V_{GS} = 4.5V, I_D = 360mA$ |
| | | | 6.4 | 9.5 | Ω | $V_{GS} = 2.4V, I_D = 20mA$ |
| Forward Transconductance (Note 9) | g _{fs} | 0.3 | 0.475 | - | S | $V_{DS} = 10V, I_D = 0.3A$ |
| Diode Forward Voltage (Note 7) | V_{SD} | | | 0.97 | V | $T_{J}=+25$ °C , $I_{S}=360$ mA, $V_{GS}=0$ V |
| DYNAMIC CHARACTERISTICS (Notes 8 & 9) | | | | | | |
| Input Capacitance | Ciss | - | 72 | 1 | рF | V 05 V V 0V |
| Output Capacitance | Coss | - | 11 | 1 | рF | V _{DS} = 25 V, V _{GS} = 0V - f = 1MHz |
| Reverse Transfer Capacitance | C _{rss} | | 3.6 | 1 | рF | 1 – 1101112 |
| Total Gate Charge | Q_g | - | 2.6 | 3.65 | nC | V 10V V 05V |
| Gate-Source Charge | Q_{gs} | - | 0.2 | 0.28 | nC | $V_{GS} = 10V$, $V_{DS} = 25V$ |
| Gate-Drain Charge | Q_{gd} | - | 0.5 | 0.7 | nC | I _D = 360mA(refer to test circuit) |
| Reverse Recovery Time (Note 9) | t _{rr} | - | 186 | 260 | ns | T _J =+25 ℃, IF=360A, |
| Reverse Recovery Charge (Note 9) | Q_{rr} | - | 34 | 48 | nC | di/dt= 100A/µs |
| Turn-On Delay Time | t _{d(on)} | - | 1.25 | - | ns | |
| Turn-On Rise Time | t _r | - | 1.7 | - | ns | $V_{DD} = 30V, V_{GS} = 10V$ |
| Turn-Off Delay Time | | - | 11.40 | - | ns | $I_D = 360 \text{mA}, R_G = 50 \Omega$ - (refer to test circuit) |
| Turn-Off Fall Time | t _{d(off)} | - | 3.5 | - | ns | (refer to test circuit) |

Notes:

- 7. Measured under pulsed conditions. Width=300µs. Duty cycle ≤ 2%.
 8. Switching characteristics are independent of operating junction temperature.
 9. For design aid only, not subject to production testing.

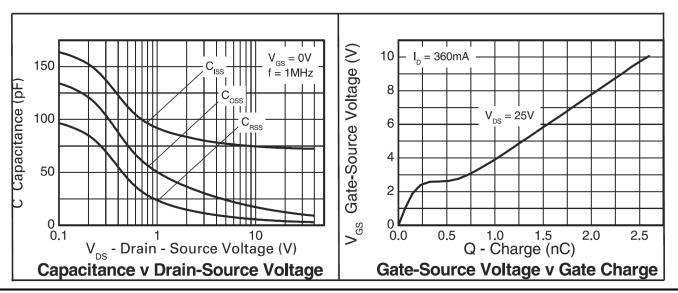


Typical Characteristics

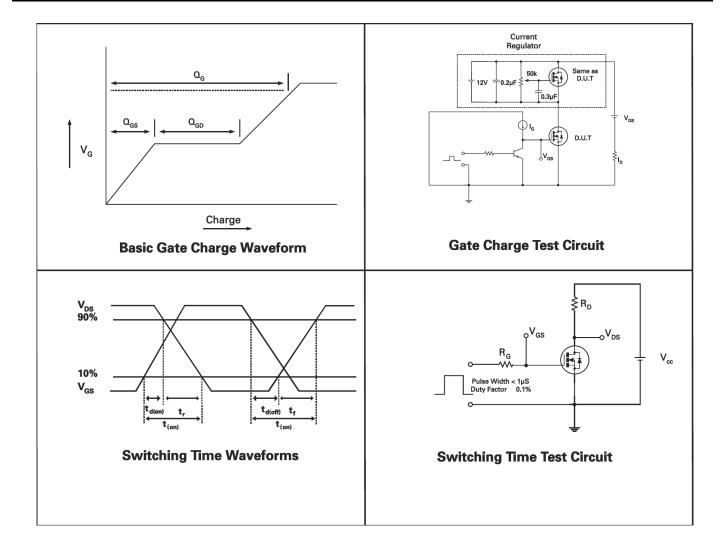




Typical Characteristics (continued)



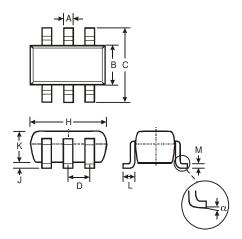
Test Circuits





Package Outline Dimensions

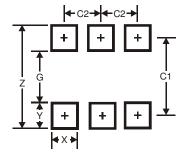
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



| SOT26 | | | | | |
|----------------------|-------|------|------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 0.35 | 0.50 | 0.38 | | |
| В | 1.50 | 1.70 | 1.60 | | |
| С | 2.70 | 3.00 | 2.80 | | |
| D | _ | _ | 0.95 | | |
| Н | 2.90 | 3.10 | 3.00 | | |
| J | 0.013 | 0.10 | 0.05 | | |
| K | 1.00 | 1.30 | 1.10 | | |
| L | 0.35 | 0.55 | 0.40 | | |
| М | 0.10 | 0.20 | 0.15 | | |
| α | 0° | 8° | | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 3.20 |
| G | 1.60 |
| Х | 0.55 |
| Υ | 0.80 |
| C1 | 2.40 |
| C2 | 0.95 |



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